

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q79041

Youichi KUKIMOTO, et al.

Appln. No.: 10/765,931

Group Art Unit: 2823

Confirmation No.: 1863

Examiner: Khiem D. NGUYEN

Filed: January 29, 2004

For: SOLDER DISPOSITION METHOD AND SOLDER BUMP FORMING METHOD

PETITION FOR EXTENSION OF TIME UNDER 37 C.F.R. § 1.136

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

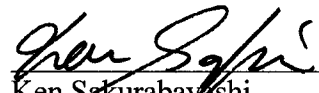
Sir:

Pursuant to 37 C.F.R. § 1.136, Applicant hereby petitions for an extension of time of three (3) month, extending the time for responding to the Office Action of February 7, 2007 from May 7, 2007 to August 7, 2007.

The statutory fee of \$900.00 is being charged to Deposit Account No. 19-4880 via EFS Payment Screen. The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,

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23373

CUSTOMER NUMBER

Date: August 7, 2007